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(54) **Title:** INTEGRATED WIRE BONDER AND 3D MEASUREMENT SYSTEM WITH DEFECT REJECTION

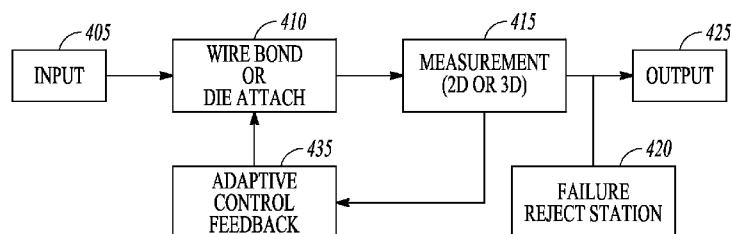


FIG. 4

(57) **Abstract:** An apparatus comprises a wire bonder system including a wire bonding device, a measuring device and a rejection device. The wire bonding device is configured to attach wire bond type electrical interconnect to an electronic assembly. A wire bond is formed between a first semiconductor device and a second electronic device to form at least a portion of the electronic assembly. The measuring device is configured to perform a three dimensional measurement associated with a wire bond, and the rejection device is configured to identify an electronic assembly for rejection according to the three dimensional wire bond measurement.

